



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20110607001A

**Qualification of Vanguard Facility as an additional FAB site source for selected devices in the 0.60UM Process
Change Notification / Sample Request**

Date: 6/6/2013
To: MOUSER PCN

Dear Customer:

The purpose of Revision A is to remove AMC7823xxx and ADS7828xxx devices from this change.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN ww admin team@list.ti.com](mailto:PCN_admin_team@list.ti.com)).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20110607001A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS7828E/250	null
AMC7823IRTAT	null
ADS7828EB/250	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN20110607001A			PCN Date:	06/07/2013
Title:	Qualification of Vanguard Facility as an additional FAB site source for selected devices in the 0.60UM process				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services
*Proposed 1st Ship Date:	06/07/2013				
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
<p>The purpose of Rev A is to remove AMC7823xxx and ADS7828xxx devices from this change. They are identified in the Product Affected Section in yellow highlight, bold font and strikethrough. These devices will continue to be sourced out of TSMC-WF2. The remaining devices are qualified for this change.</p> <p>Texas Instruments is pleased to announce the qualification of its Vanguard fabrication facility as an additional wafer FAB source for the selected devices listed in "Product Affected" section.</p>					
Currently Qualified Sites, Process, wafer dia.			Additional Site, Process, wafer dia.		
TSMC-WF2, 0.60UM, 200mm			Vanguard, VIS 0.6/0.5UM DPDM, 200mm		
The Vanguard .5um/ .6um DPDM process was previously qualified on 6/12/2006. Qualification details are provided in the Qual Data Section.					
Reason for Change:					
Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Current					
Chip Site		Chip site code (20L)		Chip country code (21L)	
TSMC-WF2		TS2		TWN	
New					
Chip Site		Chip site code (20L)		Chip country code (21L)	
Vanguard (VIS)		VAN		TWN	
Sample product shipping label (not actual product label)					
<p>TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: 39 ITEM: LBL: 5A (L)T0:1750</p> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SFE (21L) CCO: USA (22L) ASO: MLA (23L) AGO: MYS</p>					

Product Affected:				
ADS7828E/250	ADS7830IPWR	DDC112U	DDC112Y/250	
ADS7828E/250G4	ADS7830IPWRG4	DDC112U/1K	DDC112Y/250G4	
ADS7828E/2K5	ADS7830IPWT	DDC112U/1KG4	DDC112Y/2K	
ADS7828E/2K5G4	ADS7830IPWTG4	DDC112UG4	DDC112Y/2KG4	
ADS7828EB/250	AMC7823IRTAR	DDC112UK	DDC112YK/250	
ADS7828EB/250G4	AMC7823IRTARG4	DDC112UK/1K	DDC112YK/250G4	
ADS7828EB/2K5	AMC7823IRTAT	DDC112UK/1KG4	HPA00476EB/2K5	
ADS7828EB/2K5G4	AMC7823IRTATG4	DDC112UKG4		

Qualification Data:					
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.					
Qual Vehicle: ADS7830IPW (Approved: 12/6/2011)					
Wafer Fab Site:	Vanguard	Metallization:	0.3kÅTi/1kÅTiN/ 4kÅAlCu/1.4kÅTiN		
Wafer Fab Process:	VIS 0.6/0.5UM DPDM	Wafer diameter:	200mm		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test		Conditions	Sample Size		
			Lot#1	Lot#2	Lot#3
Electrical Characterization		Per Datasheet	Pass	-	-
ESD HBM		Per JEDEC	3/0	-	-
Manufacturability (Wafer Fab)		(per mfg. Site specification)	Pass	-	-
(Vanguard .5um/ .6um DPDM process Approved 6/12/2006)					
Qual Vehicle 1: DDC112Y					
Wafer Fab Site:	Vanguard	Metallization:	0.3kÅTi/1kÅTiN/ 4kÅAlCu/1.4kÅTiN		
Wafer Fab Process:	VIS 0.6/0.5UM DPDM	Wafer diameter:	200mm		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test		Conditions	Sample Size		
			Lot#1	Lot#2	Lot#3
**Steady-state Life Test		150C (300 Hrs)	116/0	-	-
Electrical Char.		Per Datasheet	Pass	-	-
**High Temp. Storage Bake		170C (168, 420hrs)	77/0	-	-
**Biased HAST		130C/85%RH (96 Hrs)	77/0	-	-
**Autoclave 121C		121C, 15 PSI (240 Hrs)	77/0	-	-
**T/C -65C/150C		-65C/+150C (1000 Cyc)	77/0	-	-
ESD HBM		Per JEDEC	3/0	-	-
ESD CDM		Per JEDEC	3/0	-	-
Electromigration		-	Pass	-	-
Hot Electron Injection		-	Pass	-	-
Die Shear		(MQ)	10/0	-	-
Latch-up		(per JESD78)	6/0	-	-
Manufacturability		(per mfg. Site specification)	Pass	-	-
**Thermal Shock		-65C/+150C (1000 Cyc)	77/0	-	-
Ball Bond Shear		50 Ball bonds, min 5 units	50/0	-	-
** Preconditioning sequence: level 2 @ 260C					

Qual Vehicle 2: OPA343U					
Wafer Fab Site:	Vanguard	Metallization:	0.3kÅTi/1kÅTiN/ 4kÅAlCu/1.4kÅTiN		
Wafer Fab Process:	VIS 0.6/0.5UM DPDM	Wafer diameter:	200mm		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test		Conditions	Sample Size		
			Lot#1	Lot#2	Lot#3
**Steady-state Life Test	150C (300 Hrs)		116/0	-	-
Wire Pull	-		10/0	-	-
Electrical Characterization	-		Pass	-	-
**Autoclave 121C	121C, 15 PSI (96 Hrs)		80/0	-	-
**T/C -65C/150C	-65C/+150C (500 Cyc)		80/0	-	-
ESD HBM	Per JEDEC		3/0	-	-
Electromigration	-		Pass	-	-
Hot Electron Injection	-		Pass	-	-
Latch-up	(per JESD78)		24/0	-	-
Bond Shear	-		40/0	-	-
** Preconditioning sequence: level 2 @ 260C					
Qual Vehicle 3: TSC2046IPW					
Wafer Fab Site:	Vanguard	Metallization:	0.3kÅTi/1kÅTiN/ 4kÅAlCu/1.4kÅTiN		
Wafer Fab Process:	VIS 0.6/0.5UM DPDM	Wafer diameter:	200mm		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test		Conditions	Sample Size		
			Lot#1	Lot#2	Lot#3
**Steady-state Life Test	150C (300 Hrs)		116/0	-	-
Electrical Char.	Per Datasheet		Pass	-	-
**High Temp. Storage Bake	170C (168, 420hrs)		77/0	-	-
**Biased HAST	130C/85%RH (96 Hrs)		77/0	-	-
**Autoclave 121C	121C, 15 PSI (240 Hrs)		77/0	-	-
**T/C -65C/150C	-65C/+150C (1000 Cyc)		77/0	-	-
ESD HBM	Per JEDEC		3/0	-	-
ESD CDM	Per JEDEC		3/0	-	-
Bond Strength	76 ball bonds, min. 3 units		76/0	-	-
Electromigration	-		Pass	-	-
Hot Electron Injection	-		Pass	-	-
Die Shear	-		10/0	-	-
Latch-up	(per JESD78)		6/0	-	-
Manufacturability	(per mfg. Site specification)		Pass	-	-
**Thermal Shock	-65C/+150C (1000 Cyc)		77/0	-	-
** Preconditioning sequence: level 2 @ 260C					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com